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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kiyoshi ARITA et al.

Serial No.: 10/036,485

Filed: January 7, 2002

For: PLASMA PROCESSING METHOD

Group Art Unit: 2829

Examiner: Scott B. Geyer

AMENDMENT

Commissioner for Patents
Washington, DC 20231

Sir:

PLEASE ACCEPT THIS AS
AUTHORIZATION TO DEBIT
OR CREDIT FEES TO
DEP. ACCT. 16-0331
PARKHURST & WENDEL

In response to the Office Action mailed December 24, 2002,
please amend the above-identified application as follows:

IN THE SPECIFICATION:

Page 1, lines 9-18, cancel and replace with:

In a process of manufacturing a silicon substrate for a
semiconductor device, the substrate is thinned during a thinning
process. This thinning process is performed, subsequently to
forming of a circuit pattern on the surface of the silicon

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